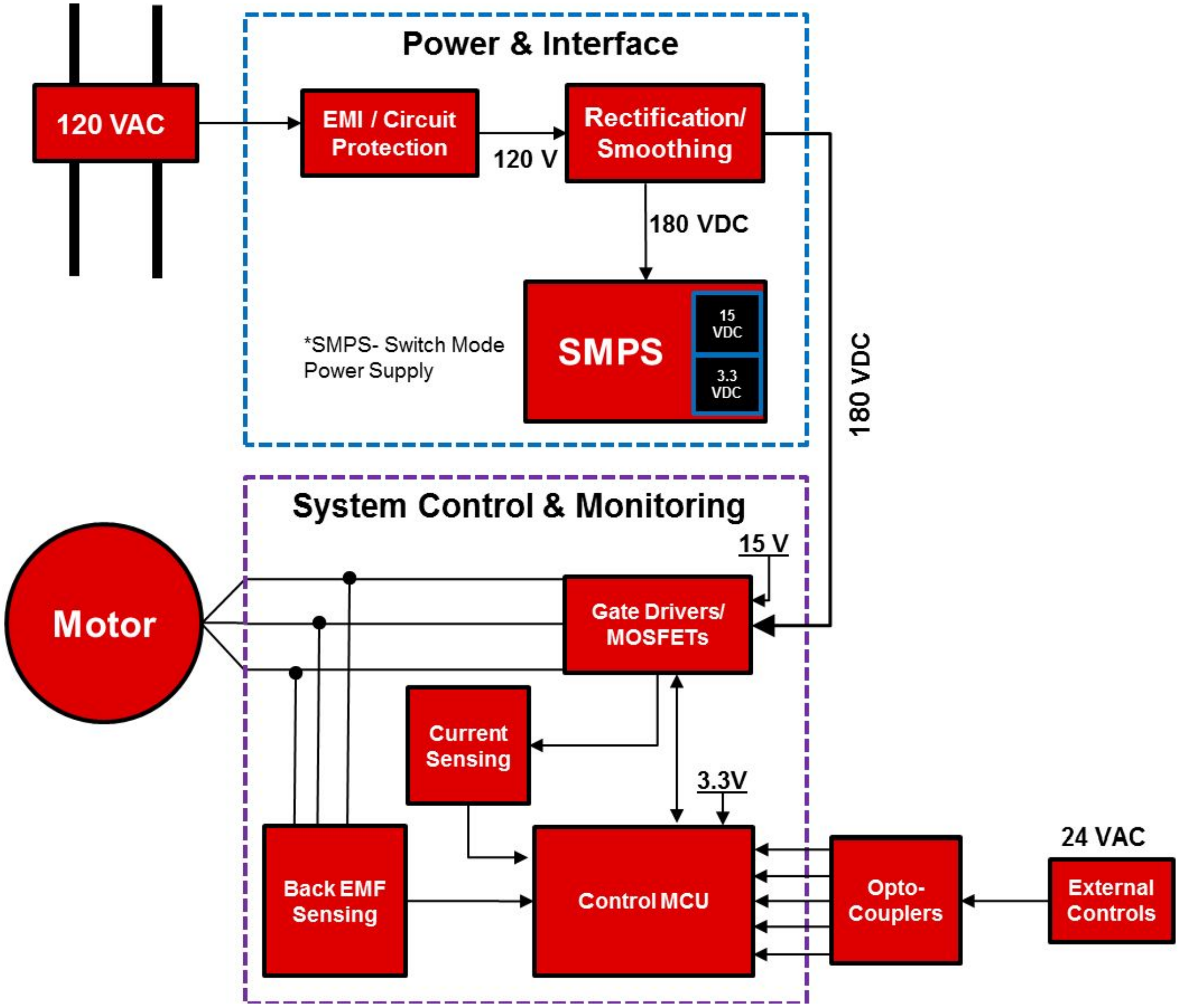

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TID #: TIDA-01353	Project Title: TIDA-01353		
Number: TIDA-01353 Rev: E1	Sheet Title:		
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 5	
Drawn By:	File: Block Diagram.SchDoc	Size: B	http://www.ti.com
Engineer: Brian Dempsey	Contact: http://www.ti.com/support		

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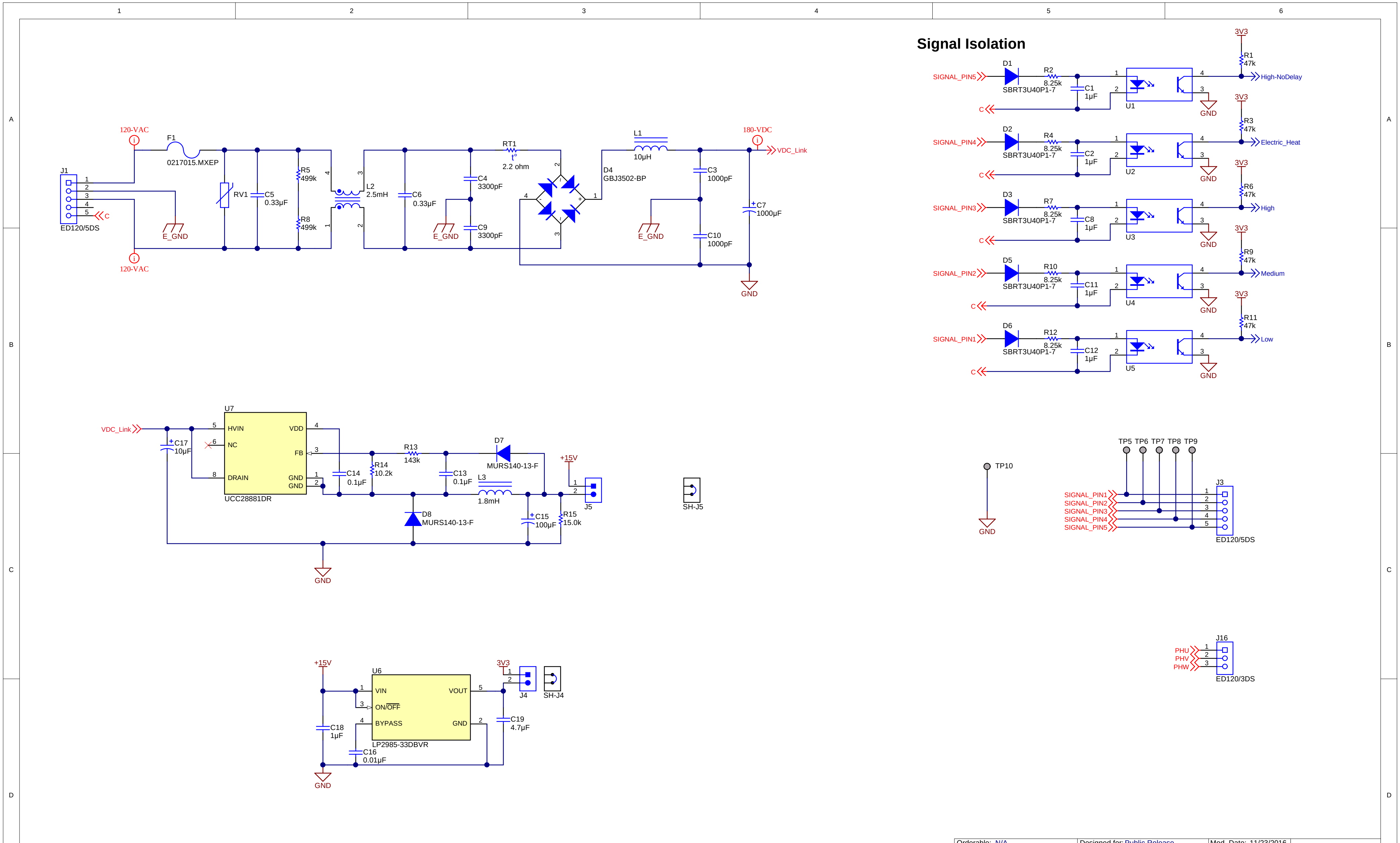

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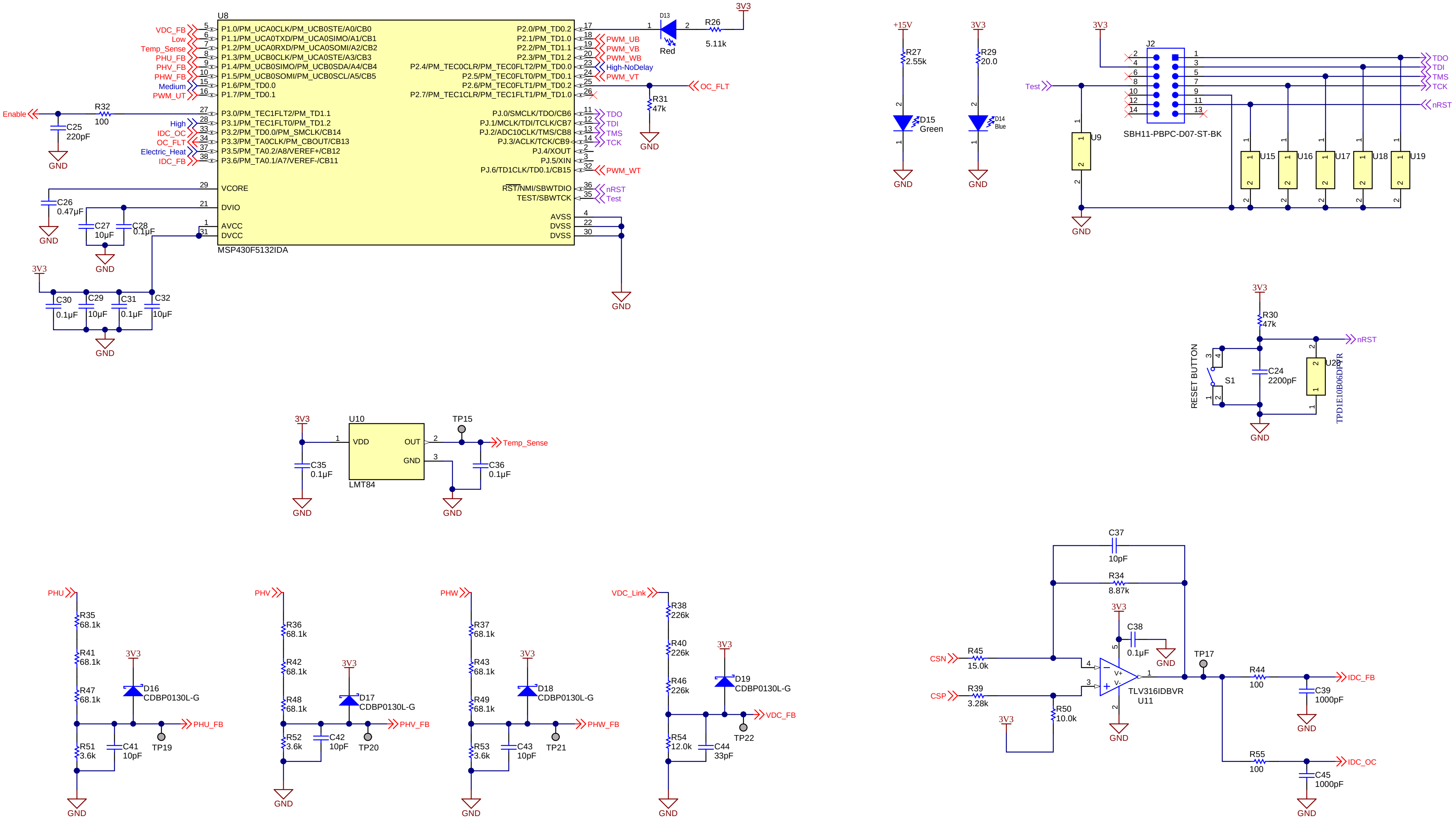
TID #: TIDA-01353	Project Title: TIDA-01353		
Number: TIDA-01353 Rev: E1	Sheet Title:		
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 5	
Drawn By:	File: TIDA-01353_System Power.SchDoc	Size: B	http://www.ti.com
Engineer: Brian Dempsey	Contact: http://www.ti.com/support		© Texas Instruments 2016



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TID #: TIDA-01353	Project Title: TIDA-01353	
Number: TIDA-01353 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 5
Drawn By:	File: TIDA-01353_MCU and Peripherals.SchDoc	Size: B
Engineer: Brian Dempsey	Contact: http://www.ti.com/support	

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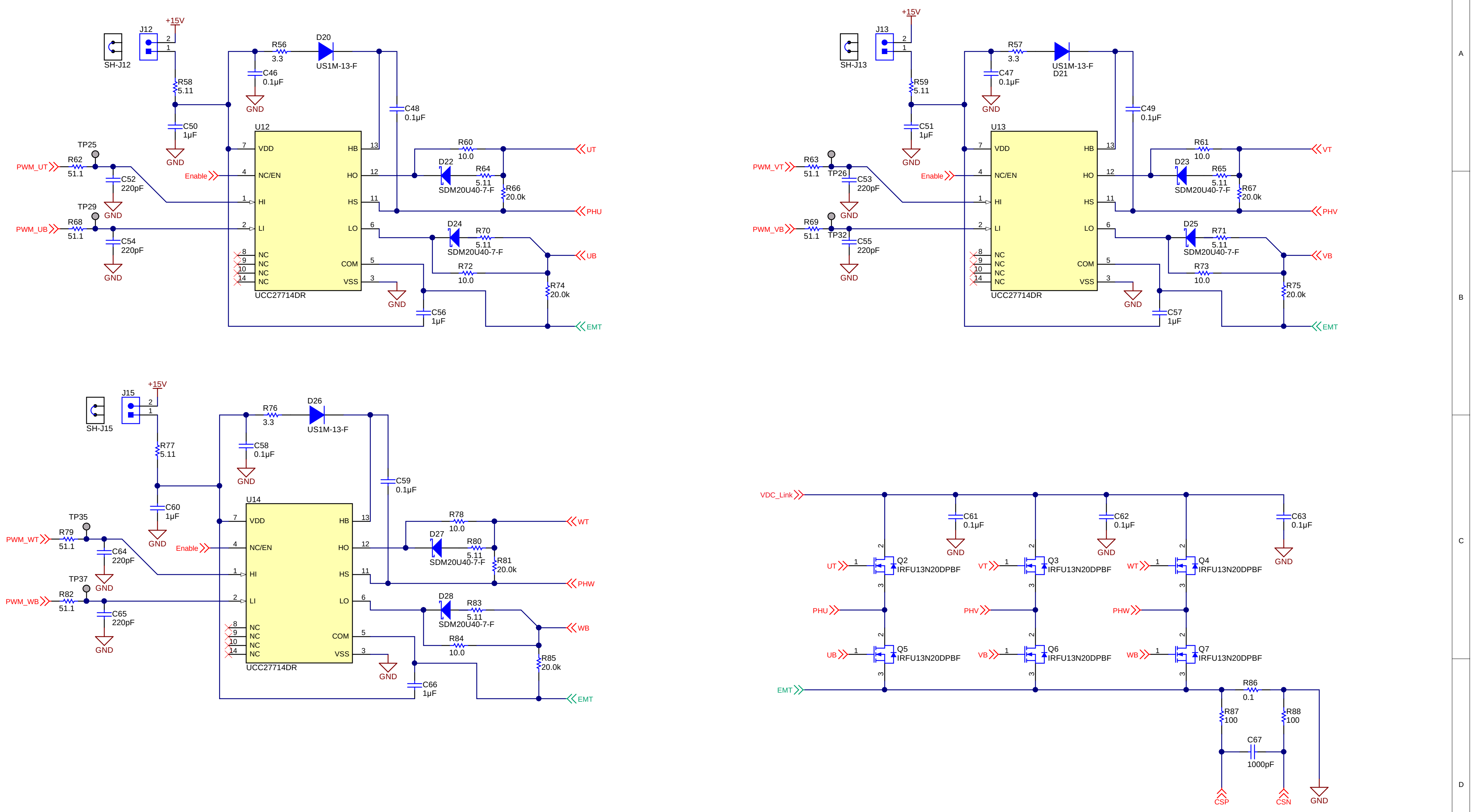

Orderable: N/A	Designed for: Public Release	Mod. Date: 11/23/2016	**TEXAS INSTRUMENTS**
TID #: TIDA-01353	Project Title: TIDA-01353		
Number: TIDA-01353 Rev: E1	Sheet Title:		
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 4 of 5	
Drawn By:	File: TIDA-01353_Motor Control.SchDoc	Size: B	http://www.ti.com
Engineer: Brian Dempsey	Contact: http://www.ti.com/support		© Texas Instruments 2016

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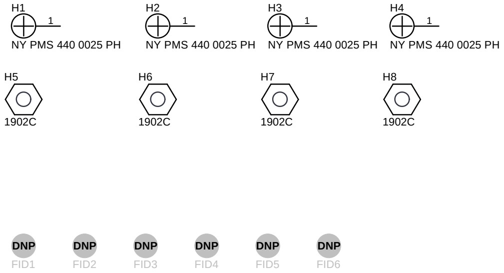

PCB Number: TIDA-01353
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer


HIGH VOLTAGE

PCB LOGO
Logo5

PCB LOGO
Logo6


Hot Surface

LBL1
PCB Label
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

Variant/Label Table

Variant	Label Text
001	-001

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: TIDA-01353	Project Title: TIDA-01353	
Number: TIDA-01353 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 5 of 5
Drawn By:	File: TIDA-01353_EVM_Hardware.SchDoc	Size: B
Engineer: Brian Dempsey	Contact: http://www.ti.com/support	

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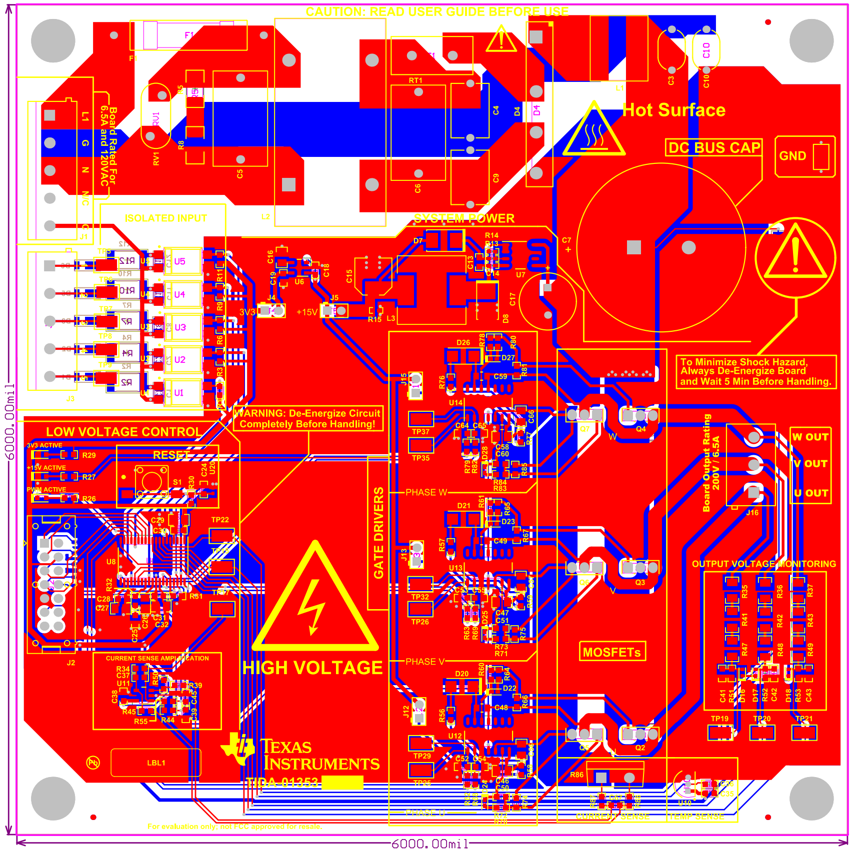
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				▨
2	Top Solder	Solder Resist	0.40mil	3.5	▨
3	Top Layer	Copper	2.80mil		▨
4	Dielectric1	FR-4 High TG	56.00mil	4.8	▨
5	Bottom Layer	Copper	2.80mil		▨
6	Bottom Solder	Solder Resist	0.40mil	3.5	▨
7	Bottom Overlay				▨

ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



1000.00mil

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE
BOARD #: TIDA-01353
REV: E1
SVN REV: Not in version control
LAYER NAME = Top Overlay, Bottom
TID #: TIDA-01353
PLOT NAME = Composite Print
GENERATED : 11/23/2016 8:41:29 AM
TEXAS INSTRUMENTS

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DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 22 MIL
MINIMUM ANNULAR RING 0.15mm (6MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
☐ FR-408 ☒ FR-4 High Tg ☐ OTHER ____
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER ____
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ____
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ____

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER ____

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ____
SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER ____
☐ MATTE ☒ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ____

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

TEXAS INSTRUMENTS

PROJECT TITLE: TIDA-01353
DESIGNED FOR: Public Release
FILE NAME: TIDA-01353.PcbDoc
ENGINEER: Brian Dempsey
LAYOUT BY: Krypton Solutions/RS
SCALE: 1.00
ALTIUM DESIGNER VERSION: 16.1.12.290

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